

## Clock Buffer/Driver

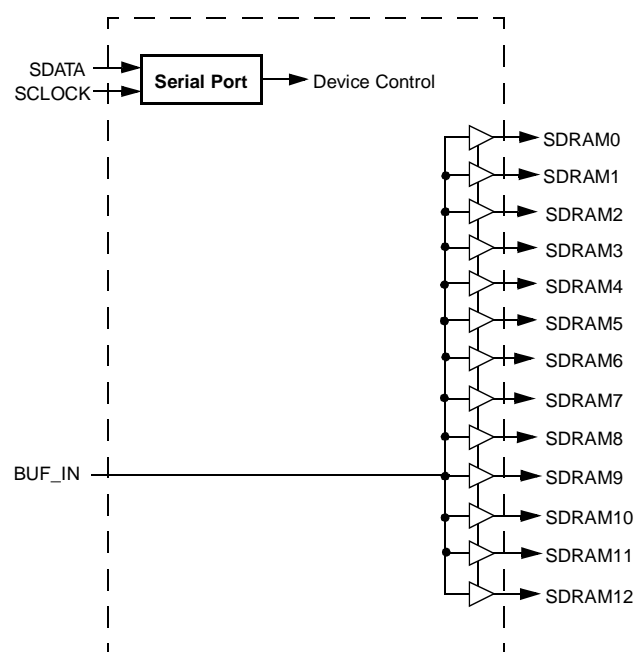
### Features

- Thirteen skew-controlled CMOS clock outputs (SDRAM0:12)
- Supports three SDRAM DIMMs
- Ideal for high-performance systems designed around Intel®'s latest chip set
- I<sup>2</sup>C™ Serial configuration interface
- Clock Skew between any two outputs is less than 250 ps
- 1 to 5 ns propagation delay
- DC to 133 MHz operation
- Single 3.3V supply voltage
- Low power CMOS design packaged in a 28-pin, 300-mil SOIC (Small Outline Integrated Circuit)

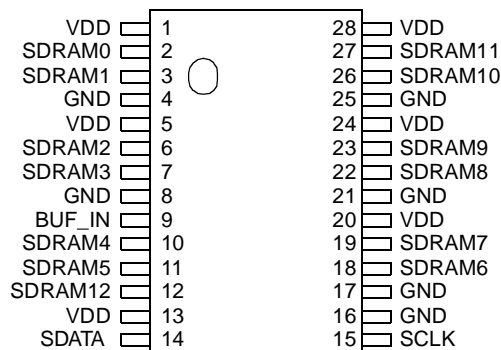
### Key Specifications

Supply Voltages: .....  $V_{DD} = 3.3V \pm 5\%$   
 Operating Temperature: .....  $0^{\circ}\text{C}$  to  $+70^{\circ}\text{C}$   
 Input Threshold: ..... 1.5V typical  
 Maximum Input Voltage: .....  $V_{DD} + 0.5V$   
 Input Frequency: ..... 0 to 133 MHz  
 BUF\_IN to SDRAM0:12 Propagation Delay: ..... 1.0 to 5.0 ns  
 Output Edge Rate: .....  $\geq 1.5$  V/ns  
 Output Clock Skew: .....  $\pm 250$  ps  
 Output Duty Cycle: ..... 45/55% worst case  
 Output Impedance: .....  $15\Omega$  typical  
 Output Type: ..... CMOS rail-to-rail

### Block Diagram



### Pin Configuration<sup>[1]</sup>



#### Note:

1. Internal pull-up resistor of 250K on SDATA and SCLK inputs (not a CMOS level).

I<sup>2</sup>C is a trademark of Philips Corporation.

Intel is a registered trademark of Intel Corporation.

**Pin Definitions**

Pin Name	Pin No.	Pin Type	Pin Description
SDRAM0:12	2, 3, 6, 7, 10, 11, 18, 19, 22, 23, 26, 27, 12	O	<b>SDRAM Outputs:</b> Provides buffered copy of BUF_IN. The propagation delay from a rising input edge to a rising output edge is 1 to 5 ns. All outputs are skew controlled to within $\pm 250$ ps of each other.
BUF_IN	9	I	<b>Clock Input:</b> This clock input has an input threshold voltage of 1.5V (typ).
SDATA	14	I/O	<b>I<sup>2</sup>C Data input:</b> Data should be presented to this input as described in the I <sup>2</sup> C section of this data sheet. Internal 250-k $\Omega$ pull-up resistor.
SCLOCK	15	I	<b>I<sup>2</sup>C clock input:</b> The I <sup>2</sup> C Data clock should be presented to this input as described in the I <sup>2</sup> C section of this data sheet. Internal 250-k $\Omega$ pull-up resistor.
VDD	1, 5, 13, 20, 24, 28	P	<b>Power Connection:</b> Power supply for core logic and output buffers. Connected to 3.3V supply.
GND	4, 8, 16, 17, 21, 25	G	<b>Ground Connection:</b> Connect all ground pins to the common system ground plane.

## Overview

The Cypress W243 is a low-voltage, thirteen-output clock buffer. Output buffer impedance is approximately 15Ω, which is ideal for driving SDRAM DIMMs

## Functional Description

### Output Drivers

The W243 output buffers are CMOS type which deliver a rail-to-rail (GND to  $V_{DD}$ ) output voltage swing into a nominal ca-

pacitive load. Thus, output signaling is both TTL and CMOS level compatible. Nominal output buffer impedance is 15Ω

### Operation

Data is written to the W243 in ten bytes of eight bits each. Bytes are written in the order shown in *Table 1*.

**Table 1. Byte Writing Sequence**

Byte Sequence	Byte Name	Bit Sequence	Byte Description
1	Slave Address	11010010	Commands the W243 to accept the bits in Data Bytes 0–6 for internal register configuration. Since other devices may exist on the same common serial data bus, it is necessary to have a specific slave address for each potential receiver. The slave receiver address for the W243 is 11010010. Register setting will not be made if the Slave Address is not correct (or is for an alternate slave receiver).
2	Command Code	“Don’t Care”	Unused by the W243, therefore bit values are ignored (“Don’t Care”). This byte must be included in the data write sequence to maintain proper byte allocation. The Command Code Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
3	Byte Count	“Don’t Care”	Unused by the W243, therefore bit values are ignored (“Don’t Care”). This byte must be included in the data write sequence to maintain proper byte allocation. The Byte Count Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
4	Data Byte 0	“Don’t Care”	Refer to Cypress clock drivers.
5	Data Byte 1		
6	Data Byte 2		
7	Data Byte 3		
8	Data Byte 4		
9	Data Byte 5	Refer to <i>Table 2</i>	The data bits in these bytes set internal W243 registers that control device operation. The data bits are only accepted when the Address Byte bit sequence is 11010010, as noted above. For description of bit control functions, refer to <i>Table 2</i> , Data Byte Serial Configuration Map.
10	Data Byte 6		
11	Data Byte 7		

## Writing Data Bytes

Each bit in the data bytes control a particular device function.  
Bits are written MSB (most significant bit) first, which is bit 7.

Table 2 gives the bit formats for registers located in Data Bytes 0–6.

**Table 2. Data Bytes 5–7 Serial Configuration Map<sup>[2]</sup>**

Bit(s)	Affected Pin		Control Function	Bit Control	
	Pin No.	Pin Name		0	1
Data Byte 5 SDRAM Active/Inactive Register (1 = Enable, 0 = Disable)					
7	11	SDRAM5	Clock Output Disable	Low	Active
6	10	SDRAM4	Clock Output Disable	Low	Active
5	N/A	Reserved	(Reserved)	-	-
4	N/A	Reserved	(Reserved)	-	-
3	7	SDRAM3	Clock Output Disable	Low	Active
2	6	SDRAM2	Clock Output Disable	Low	Active
1	3	SDRAM1	Clock Output Disable	Low	Active
0	2	SDRAM0	Clock Output Disable	Low	Active
Data Byte 6 SDRAM Active/Inactive Register (1 = Enable, 0 = Disable)					
7	27	SDRAM11	Clock Output Disable	Low	Active
6	26	SDRAM10	Clock Output Disable	Low	Active
5	23	SDRAM9	Clock Output Disable	Low	Active
4	22	SDRAM8	Clock Output Disable	Low	Active
3	N/A	Reserved	(Reserved)	-	-
2	N/A	Reserved	(Reserved)	-	-
1	19	SDRAM7	Clock Output Disable	Low	Active
0	18	SDRAM6	Clock Output Disable	Low	Active
Data Byte 7 SDRAM Active/Inactive Register (1 = Enable, 0 = Disable)					
7	N/A	Reserved	(Reserved)	-	-
6	12	SDRAM12	Clock Output Disable	Low	Active
5	N/A	Reserved	(Reserved)	--	--
4	N/A	Reserved	(Reserved)	--	--
3	N/A	Reserved	(Reserved)	--	--
2	N/A	Reserved	(Reserved)	--	--
1	N/A	Reserved	(Reserved)	--	--
0	N/A	Reserved	(Reserved)	--	--

**Note:**

- At power-up all SDRAM outputs are enabled and active. Program all reserved bits to a "0".

## How To Use the Serial Data Interface

### Electrical Requirements

Figure 1 illustrates electrical characteristics for the serial interface bus used with the W243. Devices send data over the bus with an open drain logic output that can (a) pull the bus line LOW, or (b) let the bus default to logic 1. The pull-up resistor on the bus (both clock and data lines) establish a default logic 1. All bus devices generally have logic inputs to receive data.

Although the W243 is a receive-only device (no data write-back capability), it does transmit an “acknowledge” data pulse after each byte is received. Thus, the SDATA line can both transmit and receive data.

The pull-up resistor should be sized to meet the rise and fall times specified in AC parameters, taking into consideration total bus line capacitance.

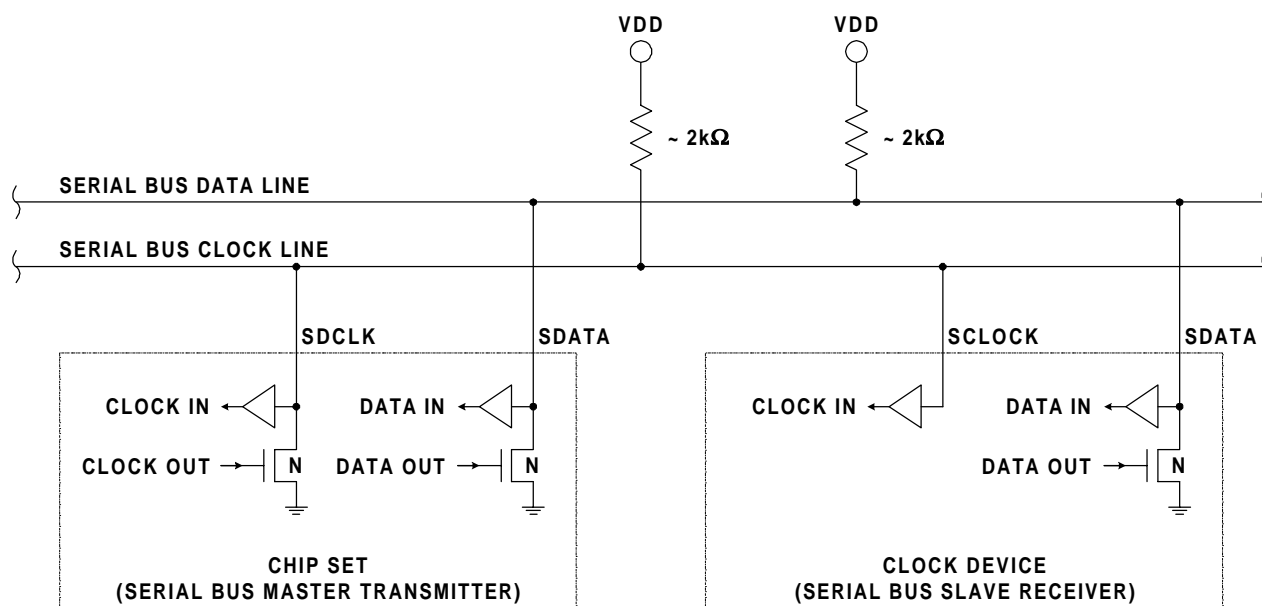


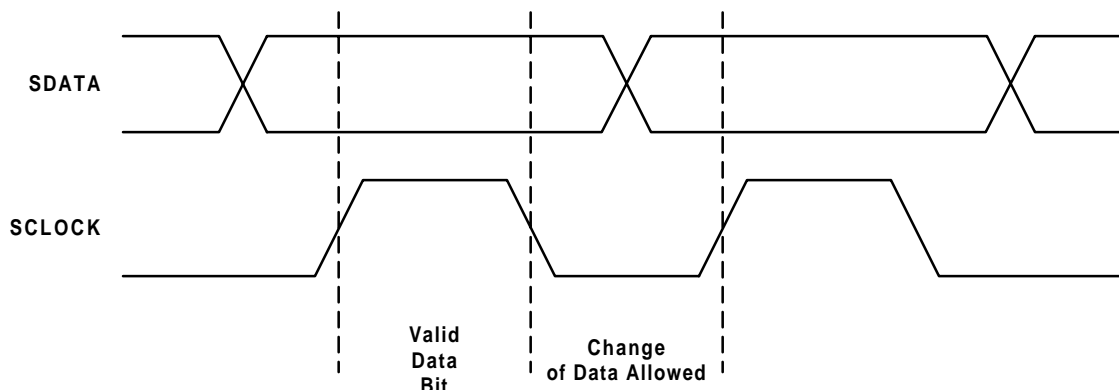
Figure 1. Serial Interface Bus Electrical Characteristics

### Signaling Requirements

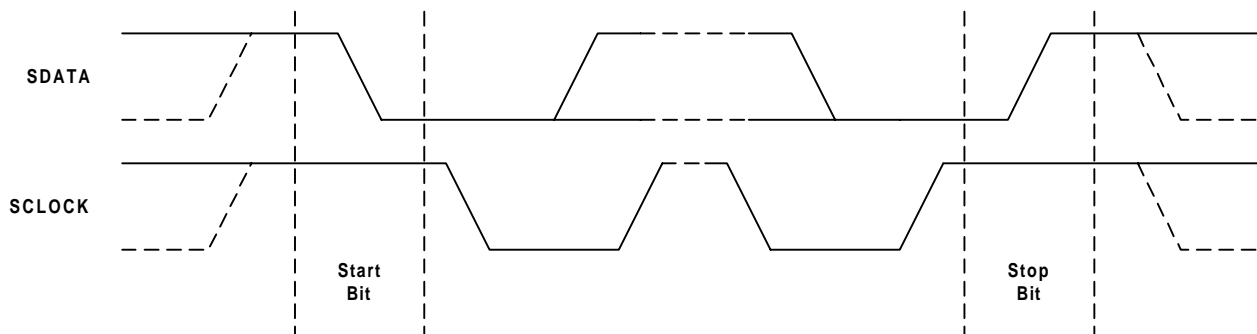
As shown in *Figure 2*, valid data bits are defined as stable logic 0 or 1 condition on the data line during a clock high (logic 1) pulse. A transitioning data line during a clock high pulse may be interpreted as a start or stop pulse (it will be interpreted as a start or stop pulse if the start/stop timing parameters are met).

A write sequence is initiated by a “start bit” as shown in *Figure 3*. A “stop bit” signifies that a transmission has ended.

As stated previously, the W243 sends an “acknowledge” pulse after receiving eight data bits in each byte as shown in *Figure 4*.



**Figure 2. Serial Data Bus Valid Data Bit**



**Figure 3. Serial Data Bus Start and Stop Bit**

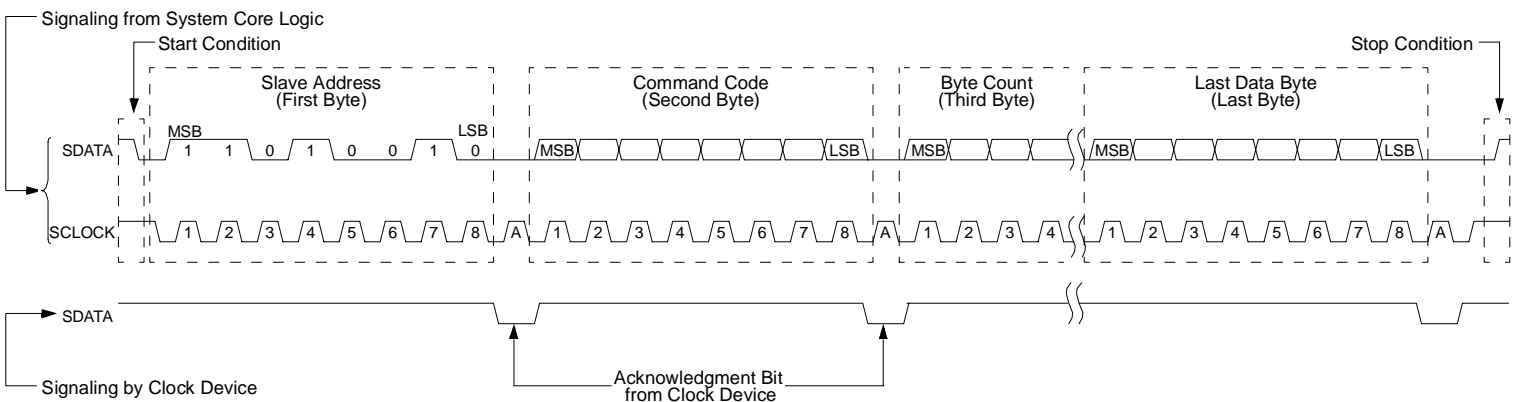


Figure 4. Serial Data Bus Write Sequence

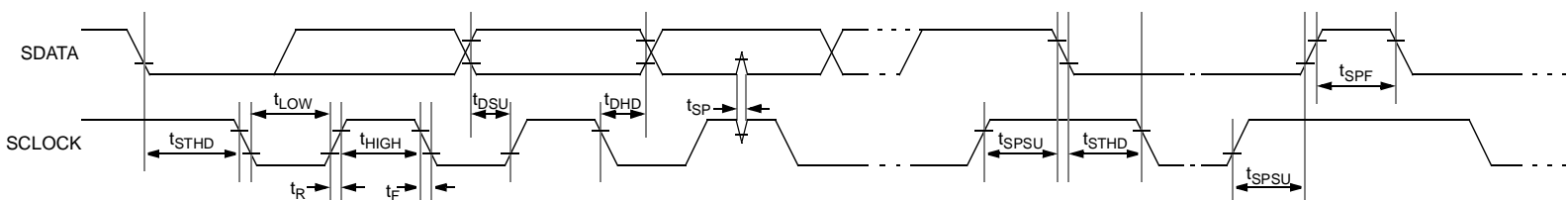


Figure 5. Serial Data Bus Timing Diagram

## Absolute Maximum Ratings

Stresses greater than those listed in this table may cause permanent damage to the device. These represent a stress rating

only. Operation of the device at these or any other conditions above those specified in the operating sections of this specification is not implied. Maximum conditions for extended periods may affect reliability.

Parameter	Description	Rating	Unit
$V_{DD}, V_{IN}$	Voltage on any pin with respect to GND	-0.5 to +7.0	V
$T_{STG}$	Storage Temperature	-65 to +150	°C
$T_B$	Ambient Temperature under Bias	-55 to +125	°C
$T_A$	Operating Temperature	0 to +70	°C

## DC Electrical Characteristics: $T_A = 0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$ , $V_{DD} = 3.3\text{V} \pm 5\%$

Parameter	Description	Test Condition/Notes	Min.	Typ.	Max.	Unit
$I_{DD}$	3.3V Supply Current	BUF_IN = 100 MHz			250	mA
<b>Logic Inputs</b>						
$V_{IL}$	Input Low Voltage		GND - 0.3		0.8	V
$V_{IH}$	Input High Voltage		2.0		$V_{DD} + 0.5$	V
$I_{ILEAK}$	Input Leakage Current, BUF_IN		-5		+5	μA
$I_{ILEAK}$	Input Leakage Current		-20		+5	μA
<b>Logic Outputs (SDRAM0:12)</b>						
$V_{OL}$	Output Low Voltage	$I_{OL} = 1\text{ mA}$			50	mV
$V_{OH}$	Output High Voltage	$I_{OH} = -1\text{ mA}$	3.1			V
$I_{OL}$	Output Low Current	$V_{OL} = 1.5\text{V}$	65	100	160	mA
$I_{OH}$	Output High Current	$V_{OH} = 1.5\text{V}$	70	110	185	mA
<b>Pin Capacitance/Inductance</b>						
$C_{IN}$	Input Pin Capacitance				5	pF
$C_{OUT}$	Output Pin Capacitance				6	pF
$L_{IN}$	Input Pin Inductance				7	nH

**AC Electrical Characteristics:**  $T_A = 0^{\circ}\text{C}$  to  $+70^{\circ}\text{C}$ ,  $V_{DD} = 3.3\text{V} \pm 5\%$  (Lump Capacitance Test Load = 30 pF)

Parameter	Description	Test Condition	Min.	Typ.	Max.	Unit
$f_{IN}$	Input Frequency		0		133	MHz
$t_R$	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1.5		4.0	V/ns
$t_F$	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1.5		4.0	V/ns
$t_{SR}$	Output Skew, Rising Edges				250	ps
$t_{SF}$	Output Skew, Falling Edges				250	ps
$t_{EN}$	Output Enable Time		1.0		8.0	ns
$t_{DIS}$	Output Disable Time		1.0		8.0	ns
$t_{PR}$	Rising Edge Propagation Delay			TBD		ns
$t_{PF}$	Falling Edge Propagation Delay			TBD		ns
$t_D$	Duty Cycle	Measured at 1.5V	45		55	%
$Z_o$	AC Output Impedance			15		$\Omega$

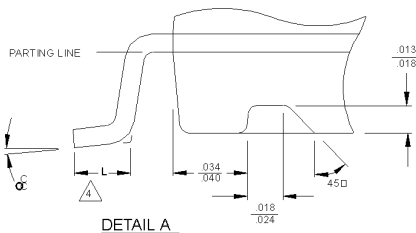
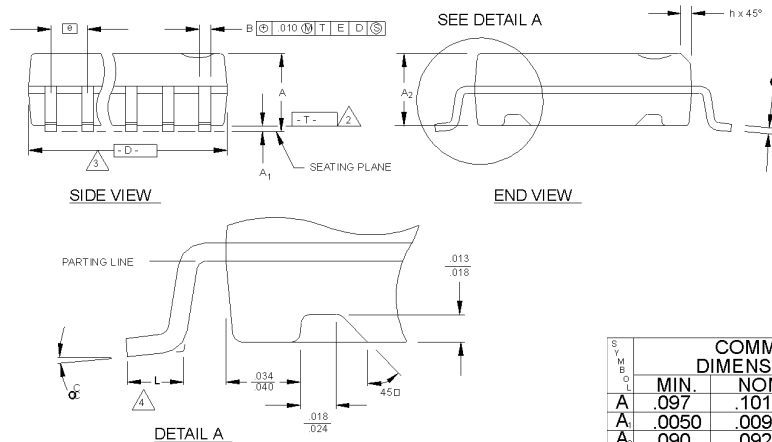
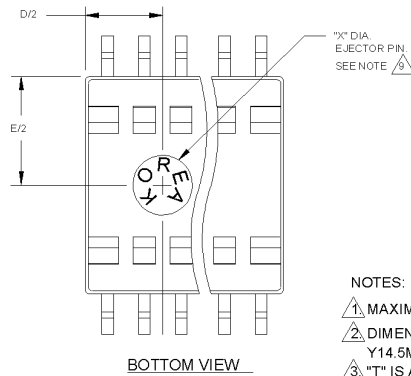
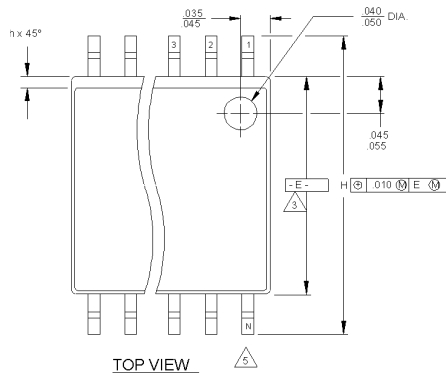
**Ordering Information**

Ordering Code	Package Name	Package Type
W243	G	28-pin SOIC (300 mils)

Document #: 38-01008-\*\*

## Package Diagram

### 28-Pin Small Outline Integrated Package (SOIC, 300 mils)



#### NOTES:

1. MAXIMUM DIE THICKNESS ALLOWABLE IS .025.
2. DIMENSIONING & TOLERANCES PER ANSI Y14.5M - 1982.
3. "T" IS A REFERENCE DATUM.
4. "D" & "E" ARE REFERENCE DATUMS AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. "L" IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
6. "N" IS THE NUMBER OF TERMINAL POSITIONS.
7. TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
8. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN .003 INCHES AT SEATING PLANE.
9. COUNTRY OF ORIGIN LOCATION AND EJECTOR PIN ON PACKAGE BOTTOM IS OPTIONAL AND DEPEND ON ASSEMBLY LOCATION.
10. THE POCKETS ON THE BOTTOM ARE OPTIONAL.
11. CONTROLLING DIMENSION: INCHES.

#### THIS TABLE IN INCHES

SYMBOL	COMMON DIMENSIONS			NOTE	VARIATIONS	3 D			5 N
	MIN.	NOM.	MAX.			MIN.	NOM.	MAX.	
A	.097	.101	.104		AA	.402	.407	.412	16
A	.0050	.009	.0115		AB	.451	.456	.461	18
A	.090	.092	.094		AC	.500	.505	.510	20
B	.014	.016	.019		AD	.602	.607	.612	24
C	.0091	.010	.0125		AE	.701	.706	.711	28
D	SEE VARIATIONS			3					
E	.292	.296	.299						
e		.050 BSC							
H	.400	.406	.410						
h	.010	.013	.016						
L	.024	.032	.040						
N	SEE VARIATIONS			5					
cc	0°	5°	8°						
X	.085	.093	.100						

#### Summary of nominal dimensions in inches:

**Body Width: 0.296**  
**Lead Pitch: 0.025**  
**Body Length: 0.625**  
**Body Height: 0.102**

#### THIS TABLE IN MILLIMETERS

SYMBOL	COMMON DIMENSIONS			NOTE	VARIATIONS	3 D			5 N
	MIN.	NOM.	MAX.			MIN.	NOM.	MAX.	
A	2.46	2.56	2.64		AA	10.21	10.34	10.46	16
A	0.127	0.22	0.29		AB	11.46	11.58	11.71	18
A	2.29	2.34	2.39		AC	12.70	12.83	12.95	20
B	0.35	0.41	0.48		AD	15.29	15.42	15.54	24
C	0.23	0.25	0.32		AE	17.81	17.93	18.06	28
D	SEE VARIATIONS			3					
E	7.42	7.52	7.59						
e		1.27 BSC							
H	10.16	10.31	10.41						
h	0.25	0.33	0.41						
L	0.61	0.81	1.02						
N	SEE VARIATIONS			5					
cc	0°	5°	8°						
X	2.16	2.36	2.54						